

In the Claims

Please amend claims 1, 2, 8, 10, 17 and 18 as follows:

1. (Amended) A slider scale package assembly comprising:

a slider/MR head; and

means for attaching to a back of the slider/MR head which turns the slider/MR head into the slider scale package assembly with at least one interconnect pad disposed at the back of the slider/MR head.

2. (Amended) A slider scale package assembly comprising:

a slider/MR head; and

a flex circuit attached to a back of the slider/MR head which turns the slider/MR head into the slider scale package assembly with at least one interconnect pad disposed at the back of the slider/MR head.

8. (Amended) The slider scale package assembly of claim 3, wherein the flex circuit

includes first, second, third, and fourth interconnect pads wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the slider/MR head includes first, second, third, and fourth bond pads wherein the at least one bond pad is one of the first, second, third or fourth bond pads.

10. (Amended) The slider scale package assembly of claim 9, wherein the first,

second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads of a head interconnect circuit match with polarities from the head interconnect circuit.

17. (Amended) The HGA of claim 16, wherein the flex circuit includes first, second,

third, and fourth interconnect pads wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pad, and the slider/MR head includes first, second, third, and fourth interconnect bonds wherein the at least one interconnect bond is one of the first, second, third or fourth interconnect bonds.

15 C 18. (Amended) The HGA of claim 17, wherein the first, second, third, and fourth interconnect pads are arranged such that the polarities of pads of the flex circuit match with polarities from the interconnect bonds.

Please insert new claims 21-23 as follows:

21. (New) A magnetic head package comprising:
a magnetic head; and
means for electrically coupling the magnetic head to an interconnect circuit of a disc drive.
22. (New) A magnetic head package comprising:
a magnetic head; and
a flex circuit coupled to a first surface of the magnetic head wherein the flex circuit has an interconnect pad for electrically coupling the flex circuit to an interconnect circuit of a disc drive.
23. (New) A package according to claim 22 wherein the flex circuit further comprises a lead that is coupled to a second surface of the magnetic head different from the first surface.

In the Drawings

Figures 1 and 6 have been amended as suggested by the Examiner. Enclosed herewith are proposed drawing changes with the above-referenced Figures edited in red pen.